

Bill of Materials

TI DESIGNS

TIPD109: Simple Thermocouple Measurement Solution Reference Design, <1°C Accurate

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number 1
1	1		TC1	Thermocouple connector	Omega	PCC-SMP-K-5	PCC-SMP-K-5
2	1		N/A	Thermocouple	Omega	5SRTC-TT-K-24-36	5SRTC-TT-K-24-36
3	1		J1	Connector, Socket 10-pin .050 R/A Sngl	Mill-Max Manu. Corp.	851-43-010-20-001000	851-43-010-20-001000
4	2		R1, R2	Resistor, 1M Ω 1/16W 5% 0402 SMD	Stackpole Electronics Inc	RMCF0402JT1M00 CT-ND	RMCF0402JT1M00
5	1		C11	Capacitor, ceramic .010 μ F 25 V X7R 0402	Yageo	311-1337-1-ND	CC0402KRX7R8BB103
6	3		C1-3	Capacitor, ceramic .10 μ F 16 V X7R 0402	TDK Corporation	445-4952-1-ND	C1005X7R1C104K
7	1		C10	Capacitor, ceramic 1.0 μ F 16 V X5R 0402	TDK Corporation	445-4978-1-ND	C1005X5R1C105K
8	2		R3, R4	Resistor, 510 Ω 1/16W .5% 0402 SMD	Susumu	RR05P510DCT-ND	RR0510P-511-D
9	10		CS, DIN, DOUT, GND, SCK, Vdd, T1+, T1-, Ain0, Ain1	Test point PC Compact .063"D YLW	Keystone Electronics	5009K-ND	5009
10	2		1, 2	Bumpon Hemisphere .50 x .14 Clear	3M	SJ5312-7-ND	SJ-5312 (CLEAR)
11	1		U1	ADS1118, RUG Package	Texas Instruments	ADS1118RUGT	ADS1118

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